

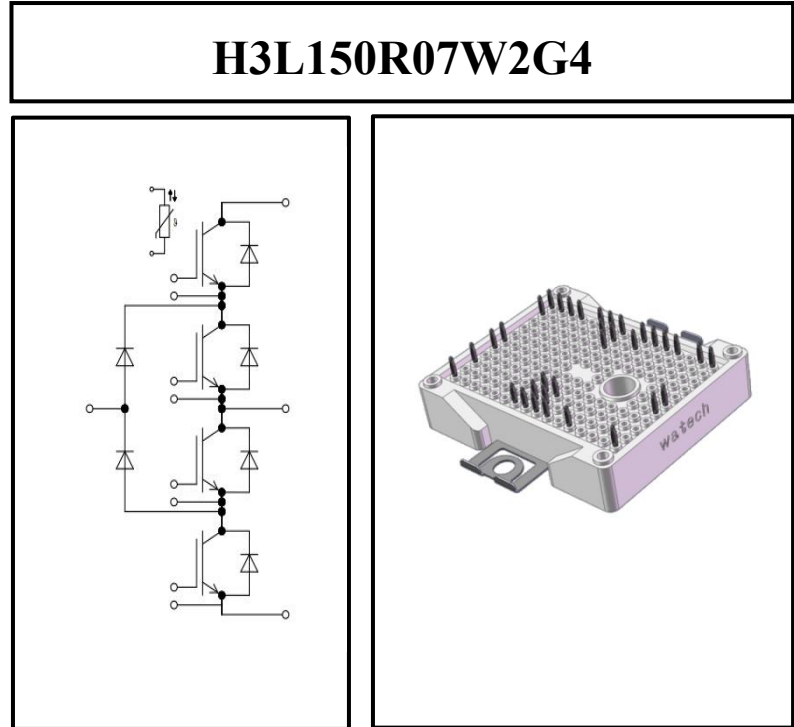
NPCI 3-LEVEL IGBT Power Transistor Module

1. Product Features:

- Low switching losses
- Low $V_{CE(sat)}$ losses
- Low stray inductance design
- Maximum junction temperature 175°C
- RoHS compliant

2. Product Applications

- 3-Level-application
- Solar String Inverter
- Energy Storage Inverter
- UPS



3. Typical Performance Parameters

Type	V_{CE}	I_C	I_F	T_{vjmax}	Marking	Package
H3L150R07W2G4	650V	150A	150A	175°C	H3L150R07W2G4	W2

4. IGBT Maximum Rated Values

Symbol	Parameters	Value	Unit	Test Conditions
V_{CES}	Collector-emitter voltage	650	V	$V_{GS} = 0V, I_{CE} = 1mA$
$I_{C\ nom}$	Continuous DC collector current	150	A	$T_C = 60^\circ C, T_{vj\ max} = 175^\circ C$
I_C		180	A	$T_C = 25^\circ C, T_{vj\ max} = 175^\circ C$
I_{CRM}	Pulsed Drain Current	300	A	$t_p = 1\ ms$
P_{tot}	Power dissipation	330	W	$T_C = 25^\circ C, T_{vj\ max} = 175^\circ C$
V_{GES}	Gate-emitter peak voltage	+/-20	V	$V_{CE} = 0V, I_{GS} = 100\mu A$

5. IGBT Characteristic Values ($T_{vj} = 25^\circ C$, unless otherwise specified)

Symbol	Parameters	Min.	Typ.	Max.	Unit	Test Conditions
$V_{CE(sat)}$	Collector-emitter saturation voltage		1.37 1.53	1.8	V	$I_{CE}=150A, V_{GE} = 15V$ $T_{vj}=25^\circ C$ $I_{CE}=150A, V_{GE} = 15V$ $T_{vj}=150^\circ C$
V_{GEth}	Gate Threshold Voltage	5.0	5.7	6.4	V	$V_{GE}=V_{CE}, I_{CE}=1mA$
Q_G	Gate-charge		1.86		μC	$V_{GE}=-15V...+15V$
R_{Gint}	Internal gate resistor		0.3		Ω	
C_{ies}	Input capacitance		17.0		nF	$f = 1\ MHz, V_{CE} = 25\ V, V_{GE} = 0\ V$
C_{res}	Reverse transfer capacitance		0.8		nF	$f = 1\ MHz, V_{CE} = 25\ V, V_{GE} = 0\ V$
I_{CES}	Collector-emitter cut-off current			1.0	mA	$V_{CE}= 650V, V_{GE}= 0V$
I_{GES}	Gate-emitter leakage current			500	nA	$V_{GE}=V_{CE}, V_{GE}=20V$

Symbol	Parameters	Min.	Typ.	Max.	Unit	Test Conditions
E_{on}	Turn-On Switching Energy		2.5 4.3		mJ	$V_{CE} = 300V, I_c = 150A$ $T_{vj} = 25^\circ C$ $R_g = 12\Omega$ $V_{GE} = \pm 15V$ $T_{vj} = 150^\circ C$
E_{off}	Turn Off Switching Energy		3.3 4.0			$V_{CE} = 300V, I_c = 150A$ $T_{vj} = 25^\circ C$ $R_g = 12\Omega$ $V_{GE} = \pm 15V$ $T_{vj} = 150^\circ C$
$t_{d(on)}$	Turn-On Delay Time		345 330		ns	$V_{CE} = 300V, I_c = 150A$ $T_{vj} = 25^\circ C$ $R_g = 12\Omega$ $V_{GE} = \pm 15V$ $T_{vj} = 150^\circ C$
t_r	Rise Time		46 54			$V_{CE} = 300V, I_c = 150A$ $T_{vj} = 25^\circ C$ $R_g = 12\Omega$ $V_{GE} = \pm 15V$ $T_{vj} = 150^\circ C$
$t_{d(off)}$	Turn-Off Delay Time		238 252			$V_{CE} = 300V, I_c = 150A$ $T_{vj} = 25^\circ C$ $R_g = 12\Omega$ $V_{GE} = \pm 15V$ $T_{vj} = 150^\circ C$
t_f	Fall Time		104 160			$V_{CE} = 300V, I_c = 150A$ $T_{vj} = 25^\circ C$ $R_g = 12\Omega$ $V_{GE} = \pm 15V$ $T_{vj} = 150^\circ C$
$R_{th(j-c)}$	Thermal Resistance from Junction to Case		0.22	0.25	$^\circ C/W$	Per IGBT
$T_{vj,op}$	Temperature under switching conditions	-40		150		

6. Reverse Diode(D1-D4) Maximum Rated Values

Symbol	Parameters	Value	Unit	Test Conditions
V_{RRM}	Repetitive peak reverse voltage	650	V	
I_F	Continuous DC forward current	150	A	
I_{FRM}	Repetitive peak forward current	300	A	$t_p = 1 \text{ ms}$

7. Reverse Diode(D1-D4) Characteristic Values

Symbol	Parameters	Min.	Typ.	Max.	Unit	Test Conditions
V_F	Forward voltage		1.5 1.22	2.1	V	$I_F = 150A, V_{GE} = 0V, T_{vj} = 25^\circ C$ $I_F = 150A, V_{GE} = 0V, T_{vj} = 150^\circ C$
I_{RM}	Peak reverse recovery current		91 162		A	$V_R = 300V, I_F = 150A, T_{vj} = 25^\circ C$ $V_{GE} = -15V, T_{vj} = 150^\circ C$ $-diF/dt = 3200A/us$
Q_{rr}	Reverse Recovery Charge		2.67 12.89		μC	$V_R = 300V, I_F = 150A, T_{vj} = 25^\circ C$ $V_{GE} = -15V, T_{vj} = 150^\circ C$ $-diF/dt = 3200A/us$
E_{rec}	Reverse recovery energy		0.4 2.18		mJ	$V_R = 300V, I_F = 150A, T_{vj} = 25^\circ C$ $V_{GE} = -15V, T_{vj} = 150^\circ C$ $-diF/dt = 3200A/us$
$R_{th(j-c)}$	Thermal Resistance from Junction to Case		0.35	0.40	$^\circ C/W$	
$T_{vj,op}$	Temperature under switching condition	-40		150		

8. Clamping Diode(D5-D6) Maximum Rated Values

Symbol	Parameters	Value	Unit	Test Conditions
V_{RRM}	Repetitive peak reverse voltage	650	V	
I_F	Continuous DC forward current	150	A	
I_{FRM}	Repetitive peak forward current	300	A	$t_p = 1 ms$

9. Clamping Diode (D5-D6) Characteristic Values

Symbol	Parameters	Min.	Typ.	Max.	Unit	Test Conditions
V_F	Forward voltage		2.0 1.6	2.35	V	$I_F = 150A, V_{GE} = 0V, T_{vj} = 25^\circ C$ $I_F = 150A, V_{GE} = 0V, T_{vj} = 150^\circ C$
I_{RM}	Peak reverse recovery current		39 98		A	$V_R = 300V, I_F = 150A, T_{vj} = 25^\circ C$ $V_{GE} = -15V, T_{vj} = 150^\circ C$ $-diF/dt = 2600A/us$
Q_{rr}	Reverse recovery charge		0.63 3.74		μC	$V_R = 300V, I_F = 150A, T_{vj} = 25^\circ C$ $V_{GE} = -15V, T_{vj} = 150^\circ C$ $-diF/dt = 2600A/us$
E_{rec}	Reverse recovery energy		0.06 0.38		mJ	$V_R = 300V, I_F = 150A, T_{vj} = 25^\circ C$ $V_{GE} = -15V, T_{vj} = 150^\circ C$ $-diF/dt = 2600A/us$
$R_{th(j-c)}$	Thermal Resistance from Junction to Case		0.37	0.43	$^\circ C/W$	
$T_{vj,op}$	Temperature under switching conditions	-40		150		

10. NTC-Thermistor Characteristic Values

Symbol	Parameters	Min.	Typ.	Max.	Unit	Test Conditions
R_{25}	Rated resistance		5		$k\Omega$	$T_c = 25^\circ C$
R/R	Deviation of R100	-5		5	%	$T_c = 100^\circ C, R_{100} = 493$
P_{25}	Power Dissipation			20	mW	$T_c = 25^\circ C$
$B_{25/50}$	B-value		3375		K	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 K))]$
$B_{25/80}$	B-value		3411		K	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 K))]$
$B_{25/100}$	B-value		3433		K	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 K))]$

11. Module

Symbol	Parameters	Value	Unit	Test Conditions
V_{ISOL}	Isolation test voltage	2.5	kV	RMS, f = 50 Hz, t = 1 min.
	Internal isolation	Al ₂ O ₃		Basic insulation (class 1, IEC 61140)
	Creepage distance	11.5	mm	terminal to heatsink
		6.3		terminal to terminal
	Clearance	10.0	mm	terminal to heatsink
		5.0		terminal to terminal
CTI	Comperative tracking index	>200		

Symbol	Parameters	Min.	Typ.	Max.	Unit	Test Conditions
L_{sCE}	Stray inductance module		15		nH	
R_{CC+EE}	Module lead resistance, terminals - chip		2.00		mΩ	
Tstg	Storage temperature	-40		125	°C	
F	Mounting force per clamp	40		80	N	

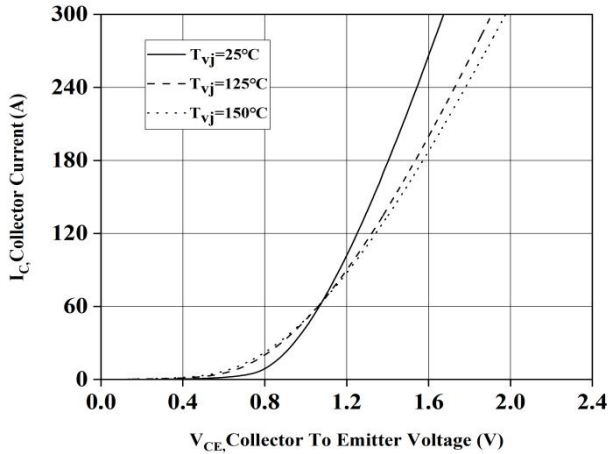


Fig.1. output characteristic IGBT, Inverter (typical)

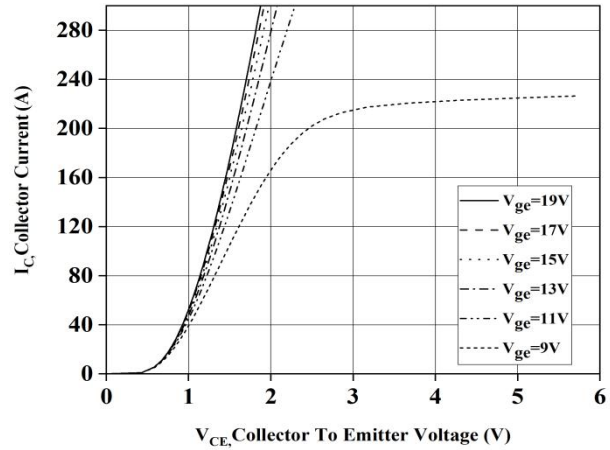


Fig.2. output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE}), V_{GE} = 15V$

$I_C = f(V_{CE}), T_{vj} = 150^\circ C$

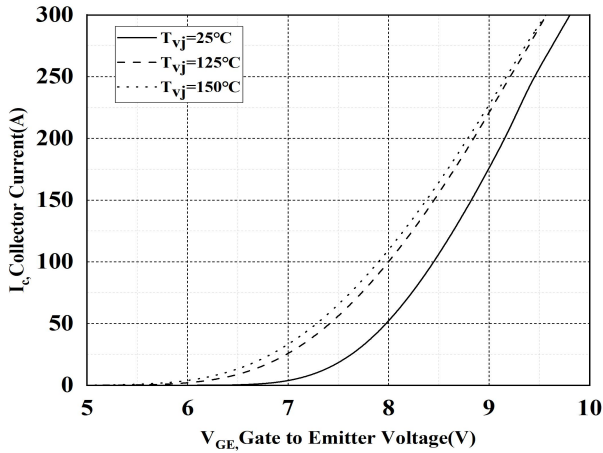


Fig.3. transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE}), V_{CE} = 20V$

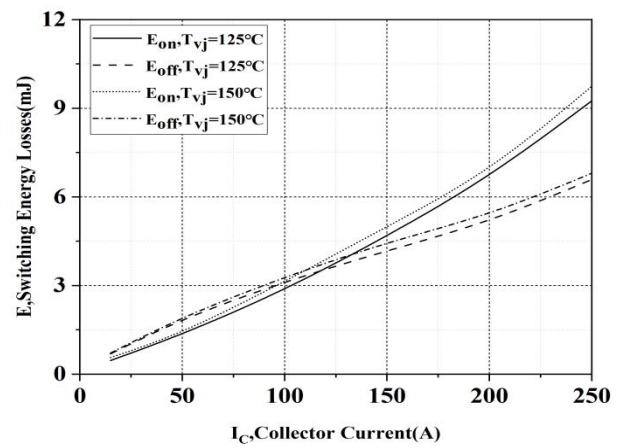


Fig.4. switching losses IGBT, Inverter (typical)

$E_{on} = f(I_C), E_{off} = f(I_C), V_{GE} = \pm 15V, R_{Gon} = 12 \Omega, R_{Goff} = 12 \Omega, V_{CE} = 300V$

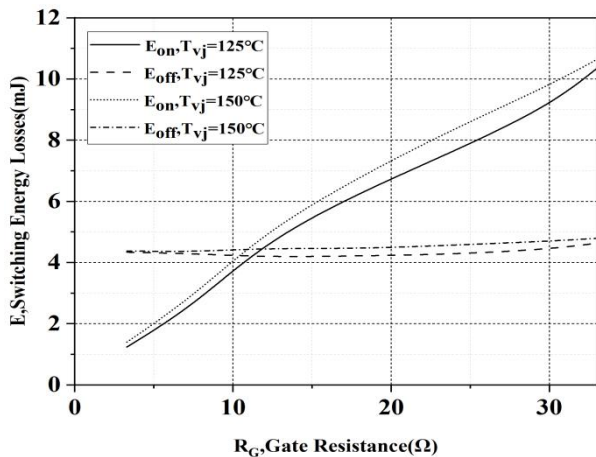


Fig.5. switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G), E_{off} = f(R_G), V_{GE} = \pm 15V, I_C = 150A, V_{CE} = 300V$

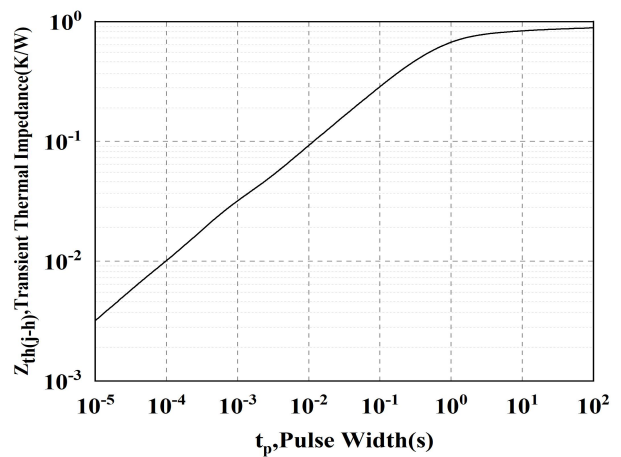
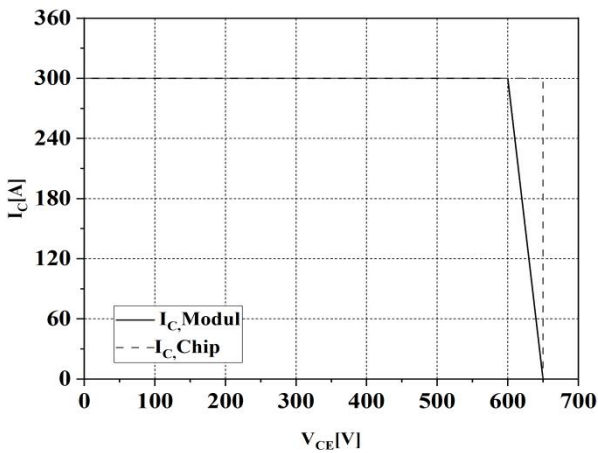


Fig.6. transient thermal impedance IGBT, Inverter

$Z_{thJH} = f(t)$



**Fig.7. reverse bias safe operating area
IGBT, Inverter(RBSOA)**

$I_C=f(V_{CE}), V_{GE}=\pm 15V, R_{Goff}=12\ \Omega, T_{vj}=150^{\circ}C$

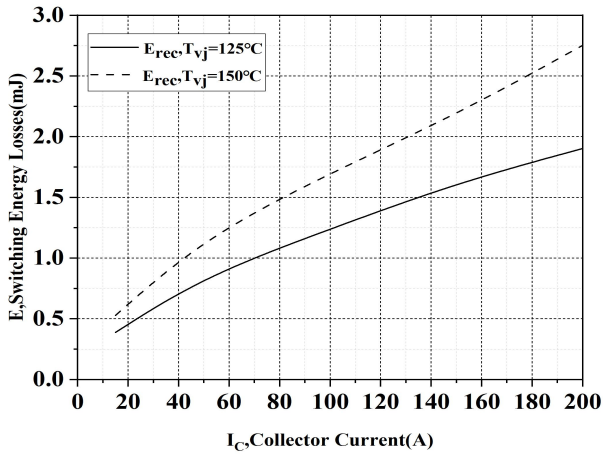
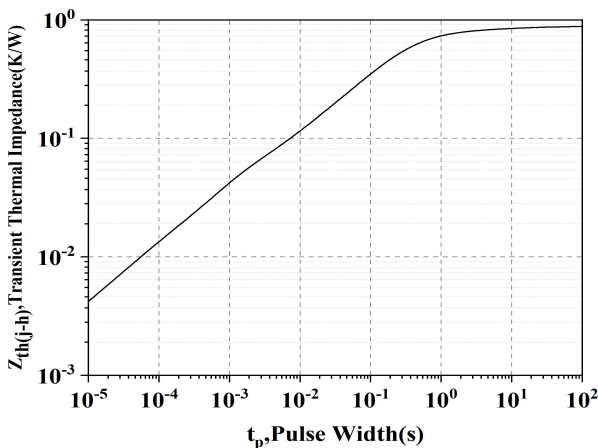


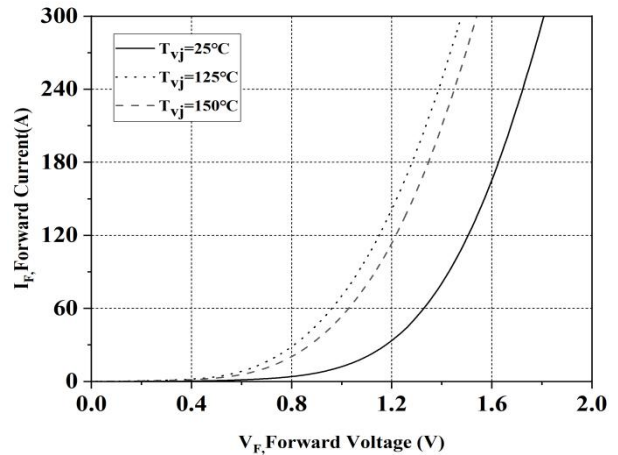
Fig.9. switching losses Diode, Inverter(typical)

$E_{rec}=f(I_F), R_{Gon}=12\ \Omega, V_{CE}=300V$



**Fig.11. transient thermal impedance
Diode, Inverter**

$Z_{thJH}=f(t)$



**Fig.8. forward characteristic of
Diode, Inverter(typical)**

$I_F=f(V_F)$

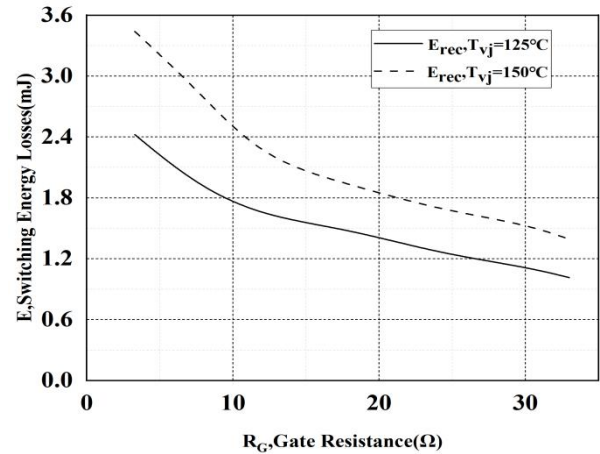
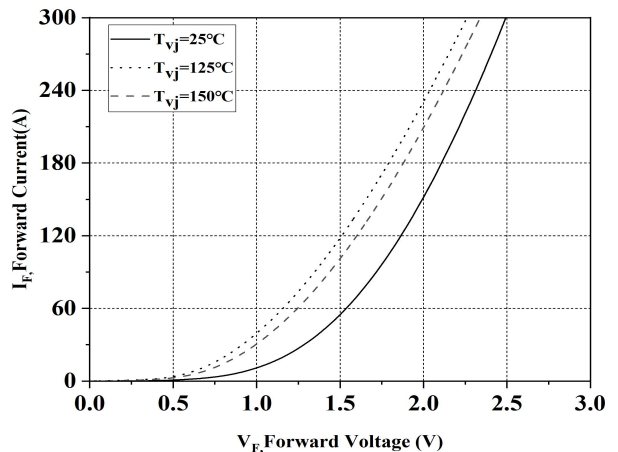


Fig.10. switching losses Diode, Inverter(typical)

$E_{rec}=f(R_G), I_F=150A, V_{CE}=300V$



**Fig.12. forward characteristic of
Diode, D5-D6(typical)**

$I_F=f(V_F)$

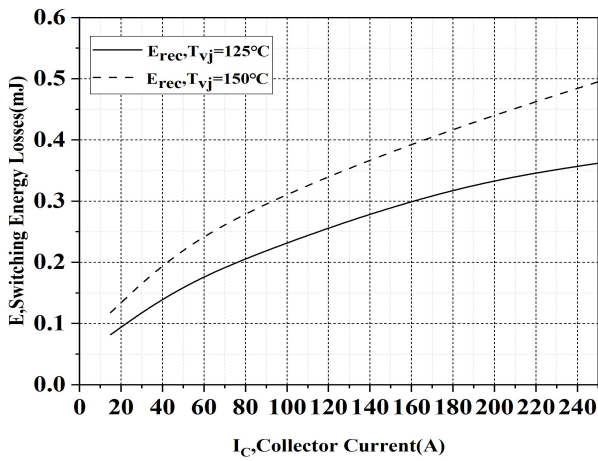


Fig.13. switching losses Diode, D5-D6 (typical)

$E_{rec} = f(I_F), R_{Gon} = 12 \Omega, V_{CE} = 300V$

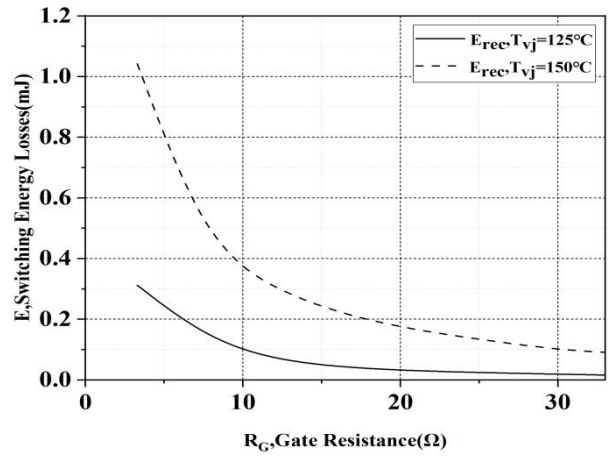


Fig.14. switching losses Diode, D5-D6 (typical)

$E_{rec} = f(R_G), I_F = 150A, V_{CE} = 300V$

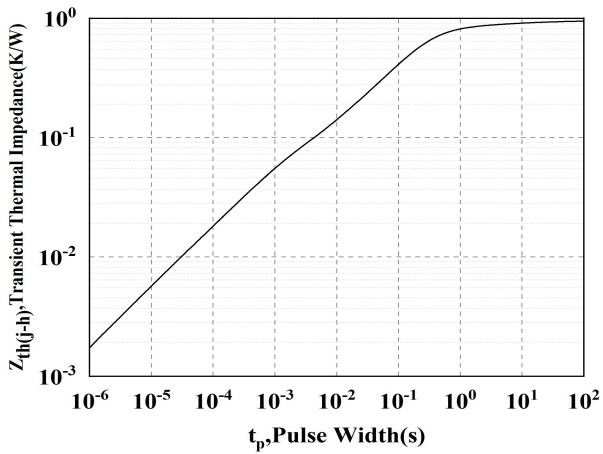


Fig.15. transient thermal impedance Diode, Inverter

$Z_{thJH} = f(t)$

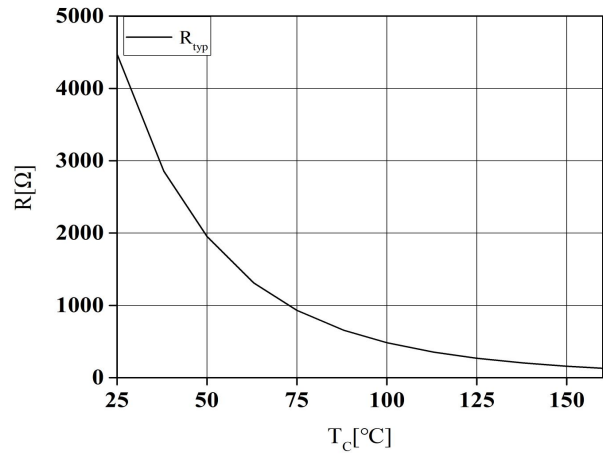


Fig.16. NTC-Thermistor-temperature characteristic (typical)

$R = f(T_C)$

14. Version Information

Version No.	Status	Date changed	Version revision record
V1.0	Preliminary version	2022/06	New build
V1.1	Final version	2023/11	Updated